

MA2QA01 (Tentative)

Silicon diodes

For power rectification

■ Features

- New Mini-power type package (2 pins)
- $V_R = 400V$, $I_F = 1.0A$

■ Absolute Maximum Ratings ($T_a = 25^\circ C$)

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	400	V
Average forward current	$I_{F(AV)}$ *1	*1 *2 0.75	A
Non-repetitive peak forward surge current	I_{FSM} *2	30	A
Junction temperature	T_j	150	$^\circ C$
Storage temperature	T_{stg}	- 55 to +150	$^\circ C$

*1 With a printed-circuit board

*2 50Hz sine half-wave (non-repetitive)

*1 Alumina board mounted (50mm × 20mm × t 1.0mm)

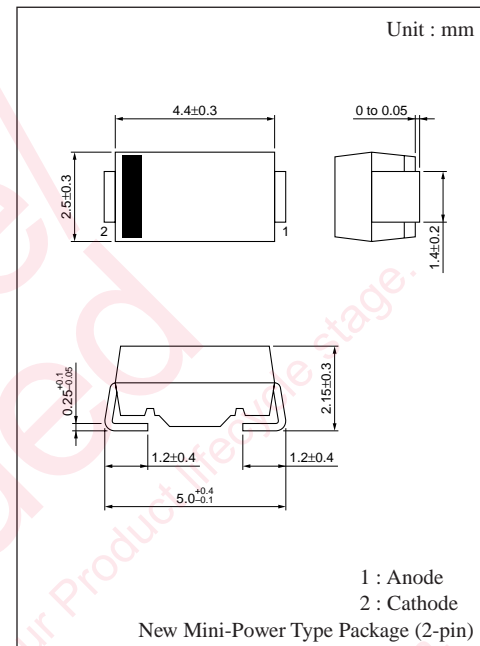
*2 Glass epoxy board mounted (50mm × 20mm × t 1.6mm)

■ Electrical Characteristics ($T_a = 25^\circ C$)

Parameter	Symbol	Condition	min	typ	max	Unit
Reverse current (DC)	I_R	$V_R = 400V$			10	μA
Forward voltage (DC)	V_F	$I_F = 1.0A$			1.1	V
Thermal resistance	$R_{th(j-a)}$ *	Alumina board mounted (50mm × 20mm × t 1.0mm)		55		$^\circ C/W$
		Glass epoxy board mounted (50mm × 20mm × t 1.6mm)		175		

❖ Rated input/output frequency : 100kHz

■ Marking

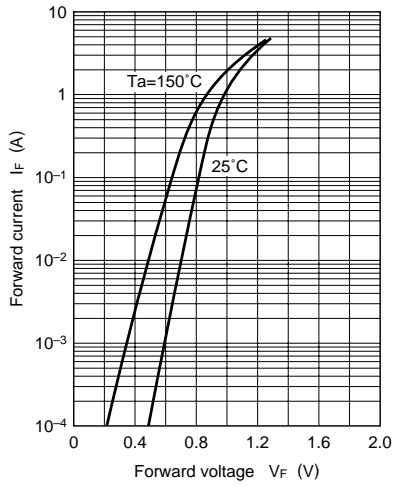


Marking Symbol : PM

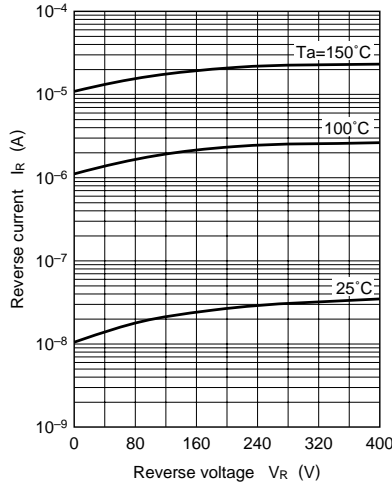
1 : Anode
2 : Cathode

New Mini-Power Type Package (2-pin)

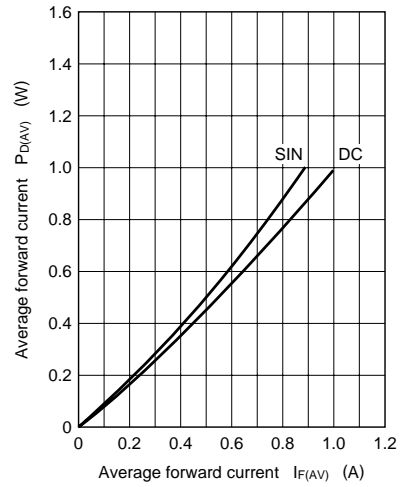
$I_F - V_F$



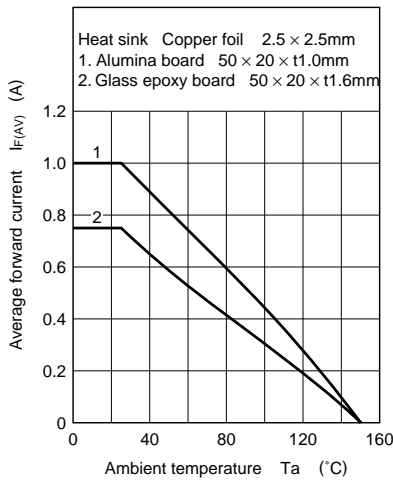
$I_R - V_R$



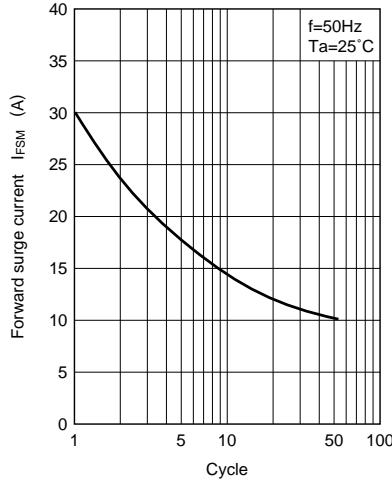
$P_{D(AV)} - I_{F(AV)}$



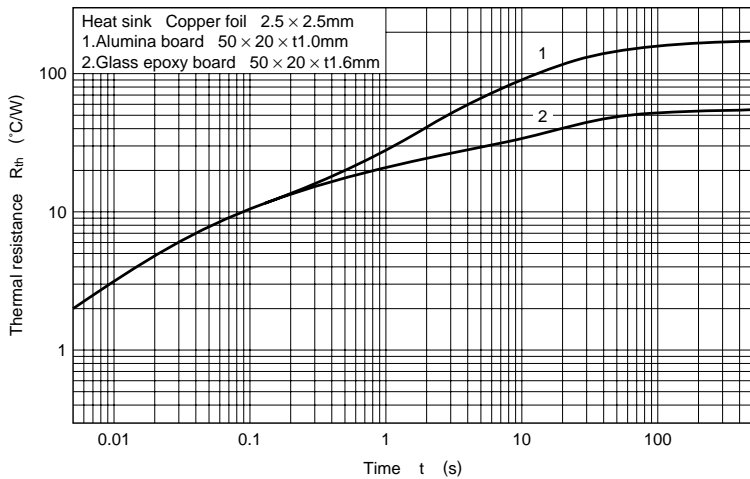
$I_{F(AV)} - T_a$



$I_{FSM} - t$



$R_{th} - t$



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